

WHAT IS CLAIMED IS:

1. A device comprising:
an integrated inductor; and
one or more electrically isolated metallic units disposed proximate to the inductor,
5 the inductor and the one or more units to satisfy a metal density rule,
wherein substantially no current is to flow within one or more of the one or more
metallic units during operation of the inductor.
2. A device according to Claim 1, wherein the inductor comprises a metal, and
10 wherein one or more of the one or more metallic units comprises the metal.
3. A device according to Claim 2, wherein the metal is copper.
4. A device according to Claim 2, wherein the metal is aluminum.
- 15 5. A device according to Claim 1, wherein the inductor comprises a plurality of
inductor elements disposed in respective ones of a plurality of device layers, and wherein the
one or more metallic units are disposed proximate to the inductor elements in the plurality of
device layers, the inductor elements and the one or more metallic units in a device layer to
20 satisfy the metal density rule for the device layer.
6. A device according to Claim 1, wherein the inductor comprises a plurality of
inductor elements, and wherein a width of one or more of the one or more metallic units is
substantially smaller than a width of one or more of the plurality of inductor elements.

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7. A device according to Claim 1, wherein the one or more metallic strips do not substantially decrease a Q of the inductor during operation of the inductor.

8. A method comprising:

5 fabricating an integrated inductor; and

 fabricating one or more electrically isolated metallic units proximate to the inductor,
the inductor and the one or more units to satisfy a metal density rule,

 wherein substantially no current is to flow within one or more of the one or more
metallic units during operation of the inductor.

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9. A method according to Claim 8, wherein the inductor comprises a metal, and
wherein one or more of the one or more metallic units comprises the metal.

10. A method according to Claim 9, wherein the metal is copper.

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11. A method according to Claim 9, wherein the metal is aluminum.

12. A method according to Claim 8, wherein fabricating the inductor comprises:

 fabricating a plurality of inductor elements in respective ones of a plurality of device
20 layers, and

 wherein fabricating the one or more metallic units comprises:

 fabricating the one or more metallic units proximate to the inductor elements in the
plurality of device layers,

 the inductor elements and the one or more metallic units in a device layer to satisfy
25 the metal density rule for the device layer.

13. A method according to Claim 8, wherein fabricating the inductor comprises:
fabricating a plurality of inductor elements, and
wherein fabricating the one or more metallic units comprises:
5 fabricating one or more of the one or more metallic units having a width
substantially smaller than a width of one or more of the plurality of inductor elements.

14. A method according to Claim 8, wherein the one or more metallic strips do not
substantially decrease a Q of the inductor during operation of the inductor.

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15. A system comprising:
a controller comprising a voltage-controlled oscillator, the voltage-controlled
oscillator comprising:

an integrated inductor; and
15 one or more electrically isolated metallic units disposed proximate to the
inductor, the inductor and the one or more units to satisfy a metal density rule,
wherein substantially no current is to flow within one or more of the one or
more metallic units during operation of the inductor; and
a double data rate memory in communication with the controller.

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16. A system according to Claim 15, further comprising:
a processor coupled to the controller and to the memory, the processor to receive
data from the controller and to transmit the data to the memory.